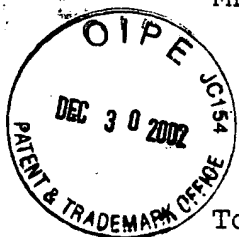


2811

MEGIC-00-012



December 17, 2002

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To: Commissioner of Patents and Trademarks

Washington, D.C. 20231

Attn: Art Unit 2811 - Douglas W. Owens

From: George O. Saile, Reg. No. 19,572

20 McIntosh Drive

Poughkeepsie, N. Y., 12603

Election
FJONES
1-9-03

Subject: | Serial No.: 09/821,546 03/30/01 |

Jin-Yuan Lee et al.

A STRUCTURE AND MANUFACTURING METHOD
OF CHIP SCALE PACKAGE

|_ Art Group: 2811 Douglas W. Owens_|

RESPONSE TO RESTRICTION REQUIREMENT

This is in response to the Restriction or Election
Requirement in the Office Action dated 12/03/02. In that
Office Action, restriction was required to one of two stated

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner of Patents and
Trademarks, Washington, D.C. 20231, on December 24, 2002.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

SBA 12/24/02

Inventions under 35 U.S.C. 121. The Inventions stated are Group I - Claims 1-5 and 7-10 to a chip-scale package, classified in Class 257, subclass 723 and Group II - Claims 11-15, 17, 19-32 and 34-41 to a process, classified in Class 438, subclass 106+.

Applicant provisionally elects to be examined the Invention described by the Examiner as Group II - Claims 11-15, 17, 19-32 and 34-41 drawn to a process classified in Class 438, subclass 106+. This election is made with traverse of the requirement under 37 C.F.R.1.143 for the reasons given in the following paragraphs.

The Examiner is respectfully requested to reconsider the Requirement for Restriction given in the Office Action. The Examiner gives the reason for the distinctness of the two inventions as (1) that the process as claimed can be used to make other and materially different products or (2) that the product as claimed can be made by another and materially different process (MPEP 806.05(f)). However, upon reading the product Claims against the process Claims one can readily see that the product Claims are directed to "a Chip-Scale Package (CSP)" and the process Claims are directed to "a method of forming a chip scale package (CSP)", it is necessary to obtain claims in both the product and method claim language. The method Claims necessarily use the product and vice versa. The

field of search must necessarily cover both the method class/subclass 438/106+ and products class 257/723 in addition to other related Classes and subclasses to provide a complete and adequate search. The fields of search for the Group I and Group II inventions are clearly and necessarily co-extensive. The Examiner's suggestion that "In the instant case the product as claimed can be made by another and materially different process, for example, the substrate and adwafer can be laser scribed instead of sawed to form the chip scale package", is very speculative and really has nothing to do with the Claims as presented in this Patent Application. Further, it is respectfully suggested that these reasons are insufficient to place the additional cost of a second Patent Application upon the Applicants. Therefore, it is respectfully requested that the Examiner withdraw this restriction requirement for these reasons.

Withdrawal of the Restriction Requirement and the Allowance of the present Patent Application is requested.

Sincerely,

A handwritten signature in black ink, appearing to be 'SBA', written over a horizontal line.

Stephen B. Ackerman, Reg. #37761